



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <small>* : Required Field</small>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2022-05-09
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	giovanni giacopello	<b>Representative Title</b>	ADG Material Declaration champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPSC40G12WLY	BF02*5G40BT7	A	998G	2022-05-09
Amount	UoM	Unit type	ST ECOPACK Grade	
5900	mg	Each	ECOPACK® 2	
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
Not Applicable	Not Applicable	.		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00832370	

Package Designator	Package Size	Nbr of instances	Shape
SIP	15.80 - 21 - 5	2	Through-hole
Comment	D0247 LONG LEADS		

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption Id.	Description

QueryList : California Prop65 list, dated 17th Dec 2021			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	amount in product (mg)	Application	ppm in product
Nickel	29.787	die - leadframe	5049

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014				
Query				Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products				false
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products				false
Hasardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
O	O	O	O	O

QueryList : REACH-17 Jan 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article / Homogeneous Material

QueryList : Responsible metals sourcing	
Query	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present in the component :	Tin,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	
Query	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	
Query	Response
The product contains adhesives identified under GB 33372	false

Stockholm Convention Persistent Organic Pollutants	
Query	Response
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I	false

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	BF02*SG408T7									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	M-01.1 Other inorganic materials	10.565	mg	supplier	die	Silicium carbide	409-21-2		9.794	mg	927022	1660				
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.179	mg	16943	30				
				supplier	metallisation	Silicon(Si)	7440-21-3		0.043	mg	4070	7				
				supplier	metallisation	Copper(Cu)	7440-50-8		0.024	mg	2272	4				
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.153	mg	14482	26				
				supplier	metallisation	Silver(Ag)	7440-22-4		0.157	mg	14860	27				
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.018	mg	1704	3				
				supplier	metallisation	Vanadium(V)	7440-62-2		0.005	mg	473	1				
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.029	mg	2745	5				
				supplier	passivation	Silicon oxide	7631-86-9		0.047	mg	4449	8				
				supplier	polymer coating	polyimide	proprietary		0.116	mg	10980	20				
				Leadframe	M-004 Copper and its alloys	3704.269	mg	supplier	alloy	Copper (Cu)	7440-50-8		3669.819	mg	990700	622003
								supplier	alloy	Iron(Fe)	7439-89-6		3.704	mg	1000	628
								supplier	metallization	Nickel (Ni)	7440-02-0		29.634	mg	8000	5023
supplier	metallization	Phosphorus (P)	7723-14-0						1.112	mg	300	188				
Soft solder	Solder	4.268	mg	supplier	solder	Tin(Sn)	7440-31-5		2.774	mg	649953	470				
				supplier	solder	Silver(Ag)	7440-22-4		1.067	mg	250000	181				
				supplier	solder	Antimony (Sb)	7440-36-0		0.427	mg	100047	72				
				supplier	wire	Aluminium (Al)	7429-90-5		4.156	mg	1000000	704				
Bonding wires	M-003 Aluminum and its alloys	4.156	mg	supplier	wire	Aluminium (Al)	7429-90-5		4.156	mg	1000000	704				
				Encapsulation	M-01.1 Other inorganic materials	2146.091	mg	supplier	mold compound	Epoxy resin	29690-82-2		1824.199	mg	850010	309186
								supplier	mold compound	Phenol resin	25068-38-6		107.326	mg	50010	18191
								supplier	mold compound	Silica	60676-86-0		128.765	mg	60000	21825
								supplier	mold compound	Fire Retardant	Proprietary		75.113	mg	35000	12731
supplier	mold compound	Carbon black	1333-86-4		10.688	mg	4980	1812								
Connections coating	Solder	30.651	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		30.651	mg	1000000	5195				